

FIG. 1

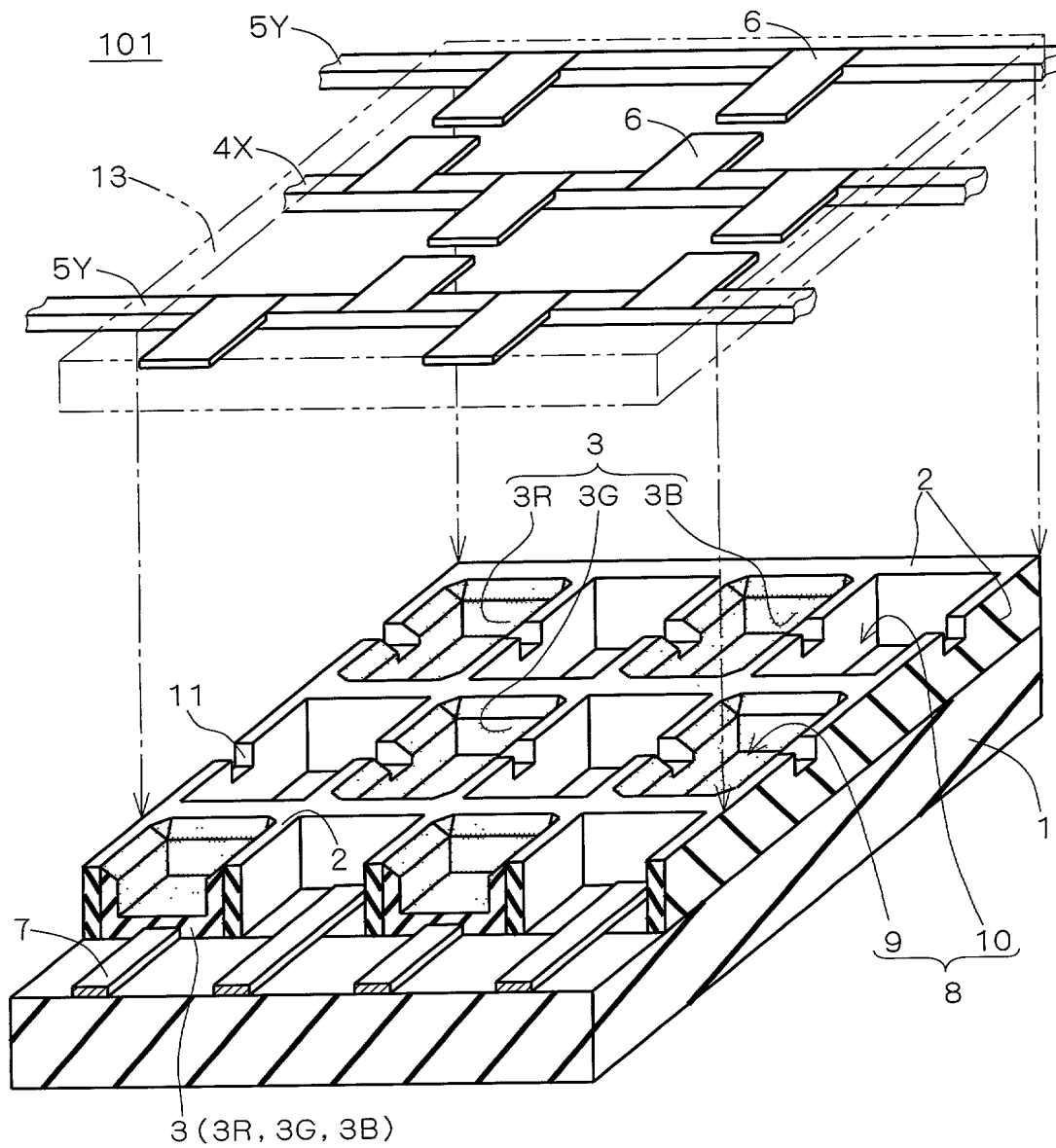


FIG. 2

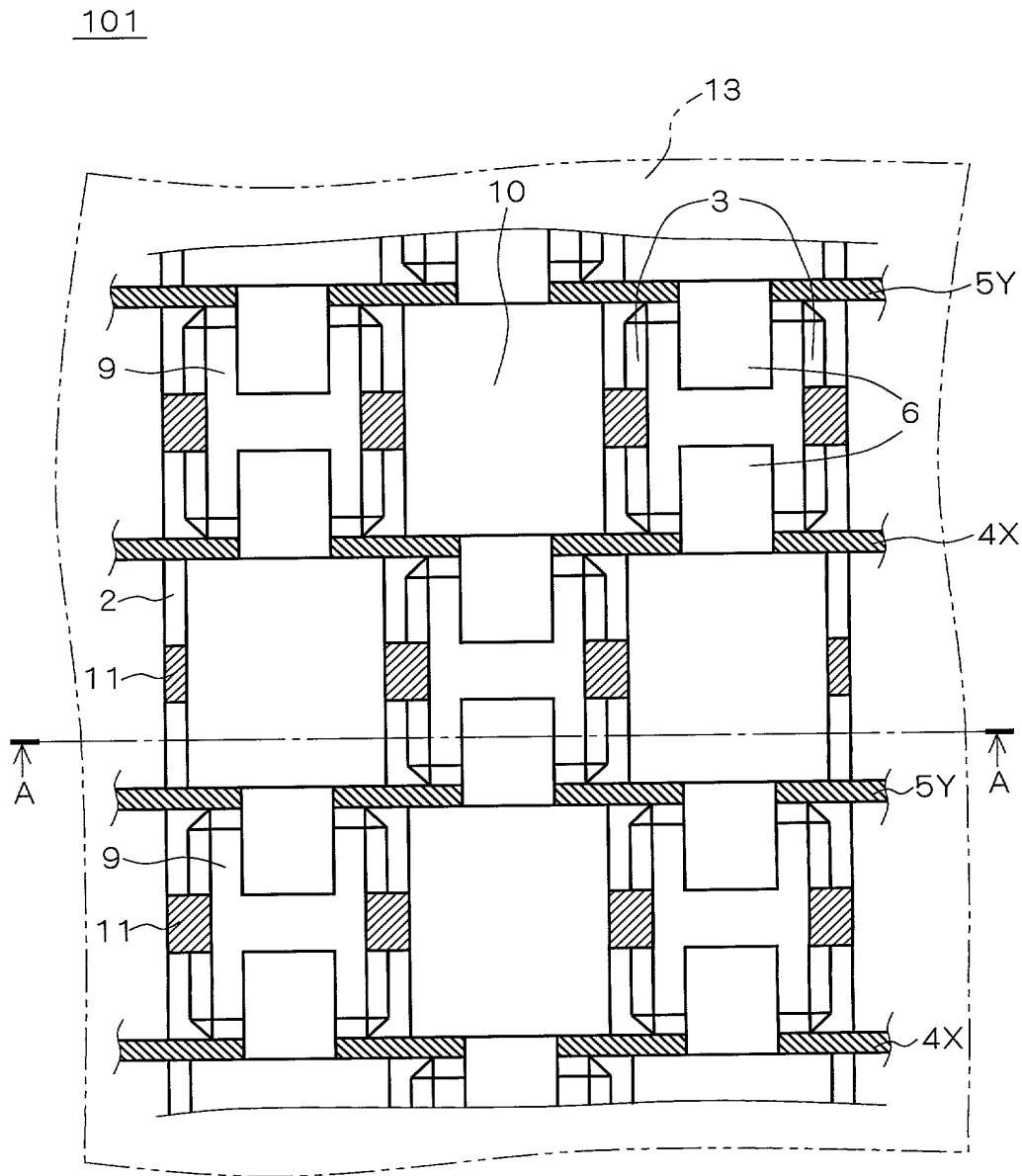


FIG. 3

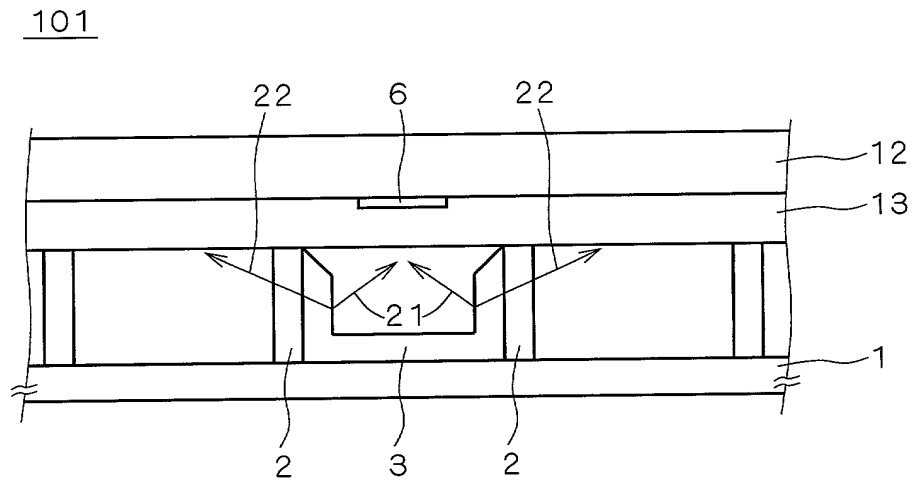
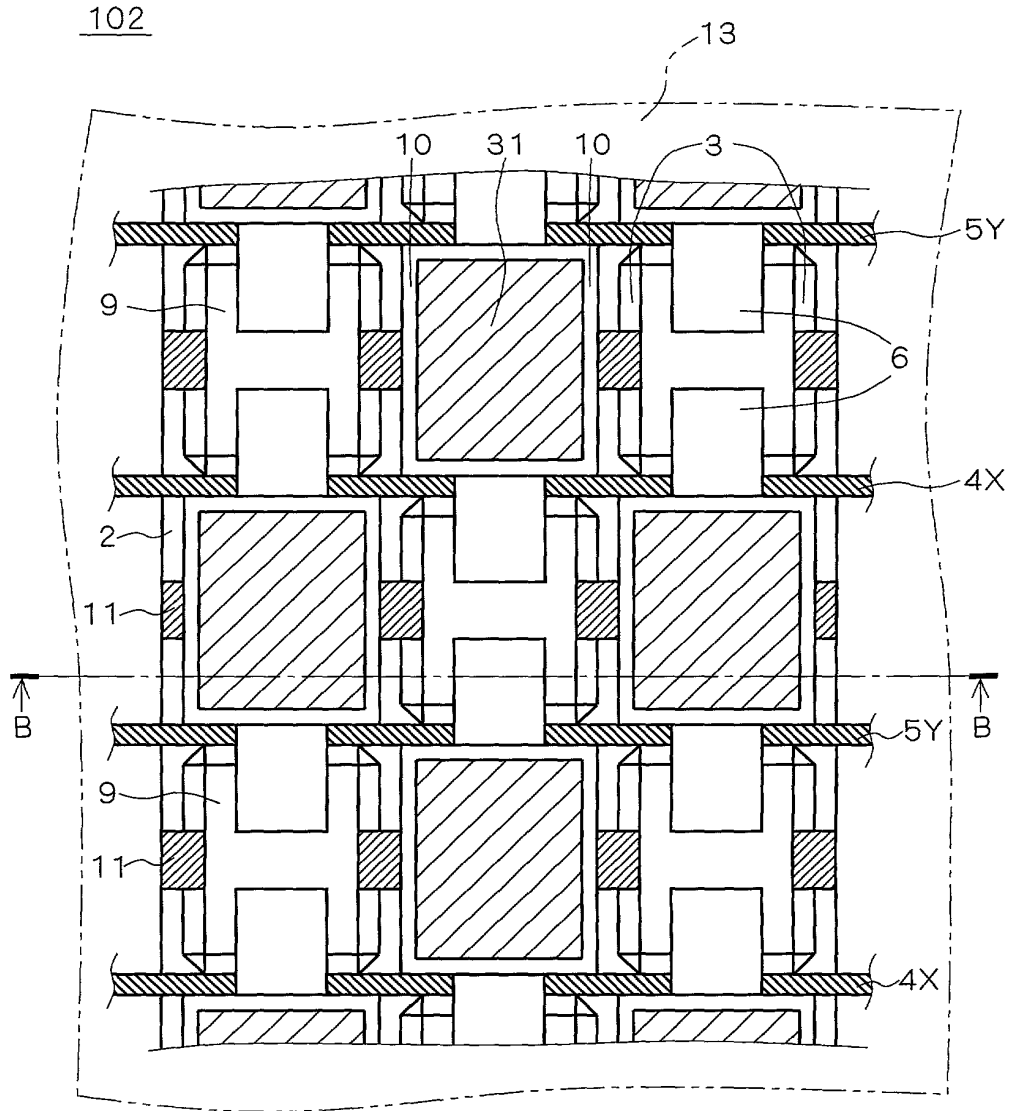


FIG. 4



F / G. 5

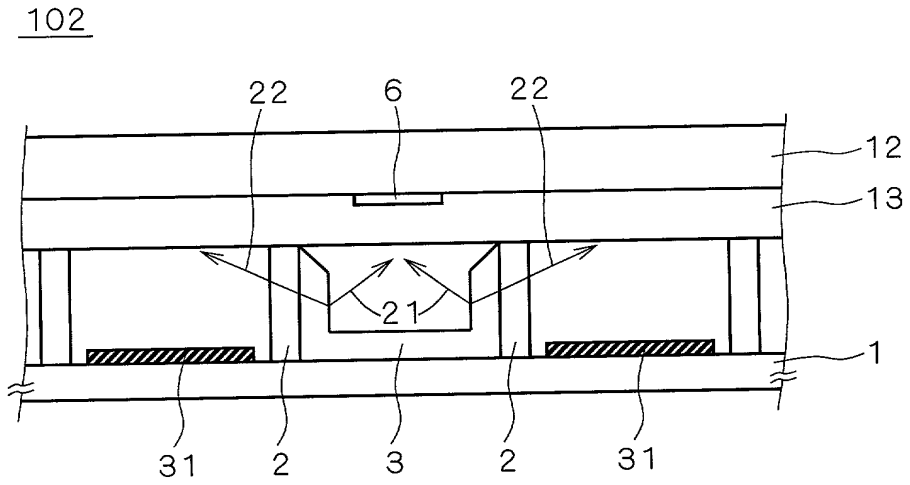
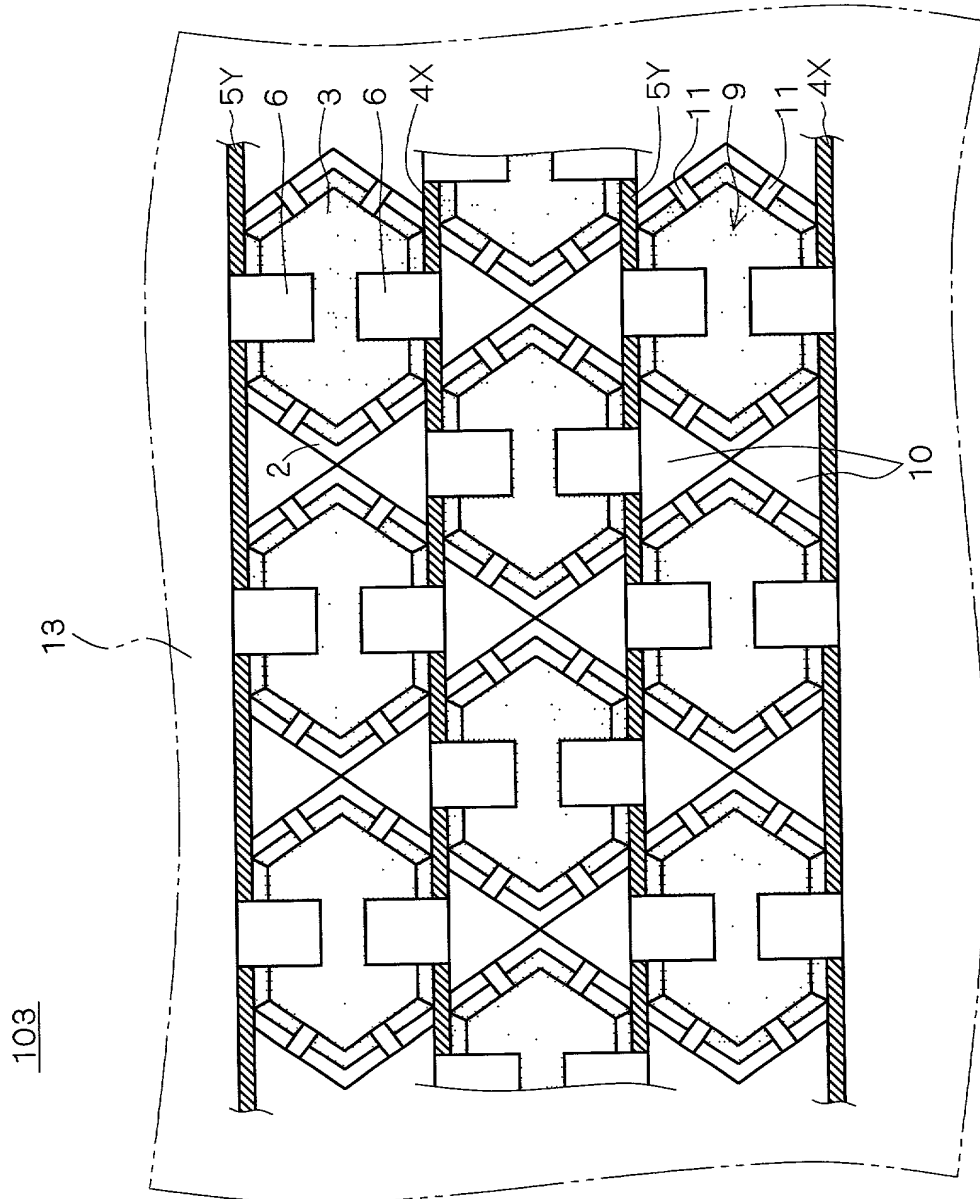


FIG. 6



103:PDP

Figure 1 illustrates a perspective view of a multi-layered substrate assembly. The assembly includes a base layer 1 with a grid of rectangular openings 2. Above this base, there are three distinct layers of conductive patterns: a first layer 3 featuring red (3R), green (3G), and blue (3B) regions; a second layer 4 with cross-shaped conductive patterns 4X; and a third layer 5 with horizontal conductive strips 5Y. A top layer 6 covers the entire structure. Other labeled components include 7, 8, 9, 10, 11, 13, and 104, which represent various structural and electrical elements of the device.

FIG. 8

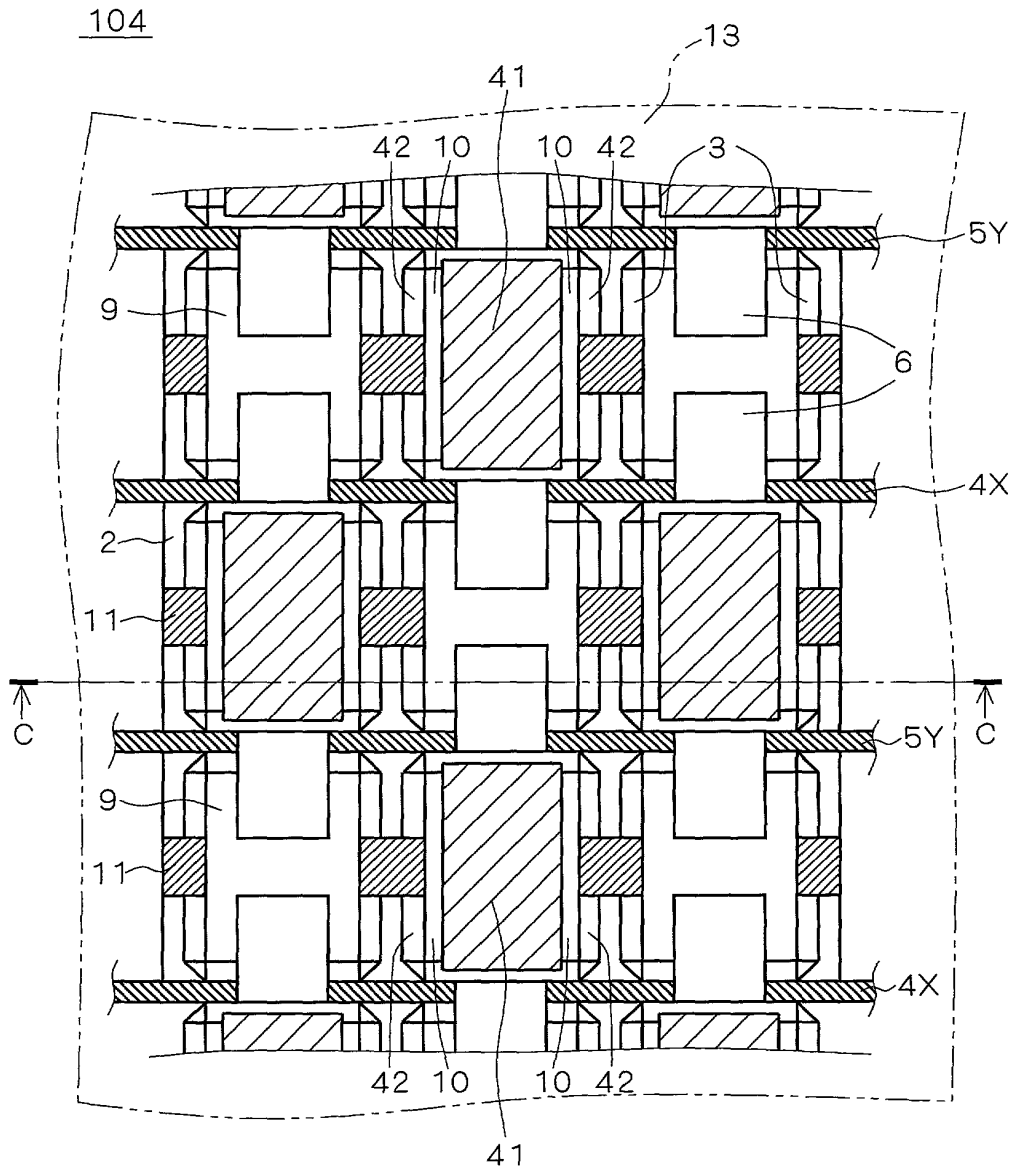


FIG. 9

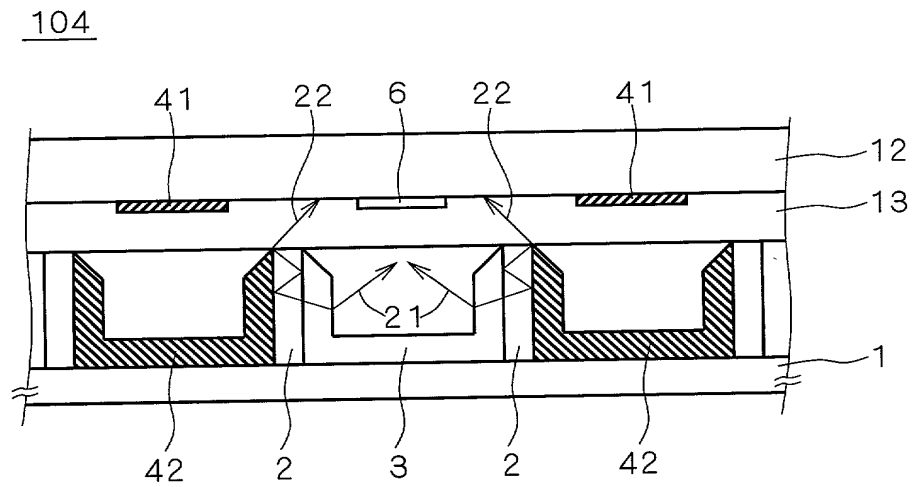


FIG. 10

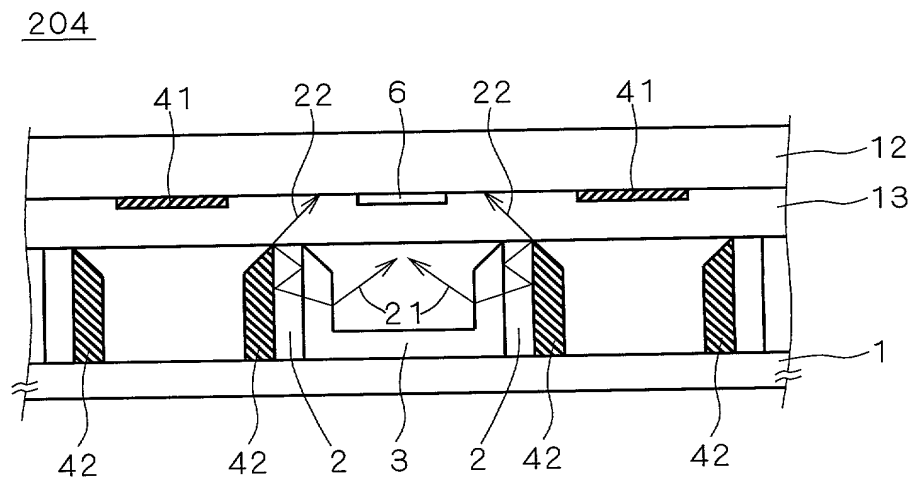


FIG. 11

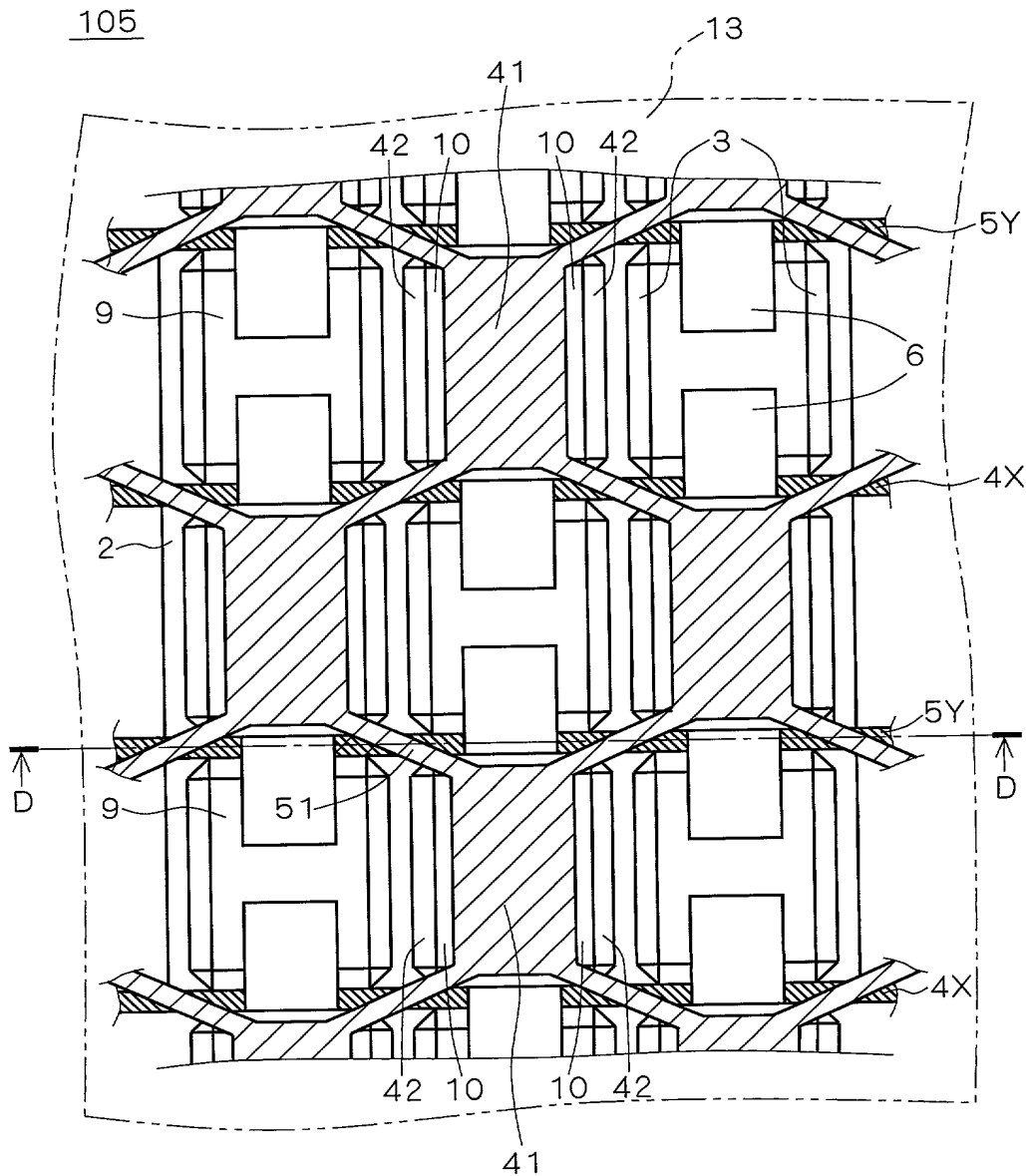


FIG. 12

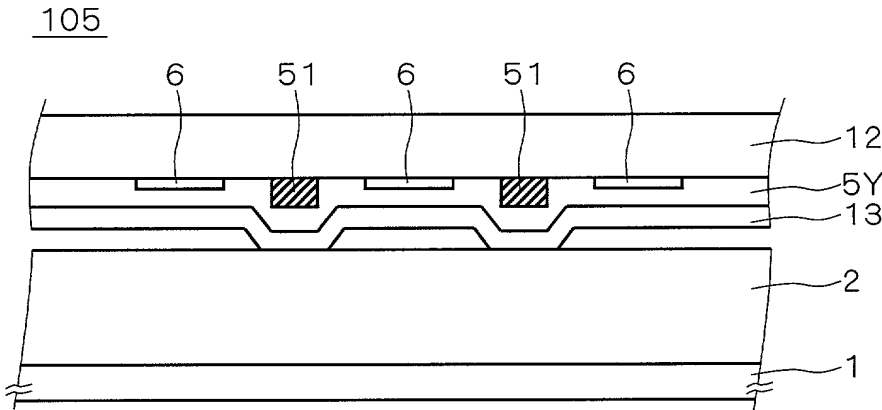
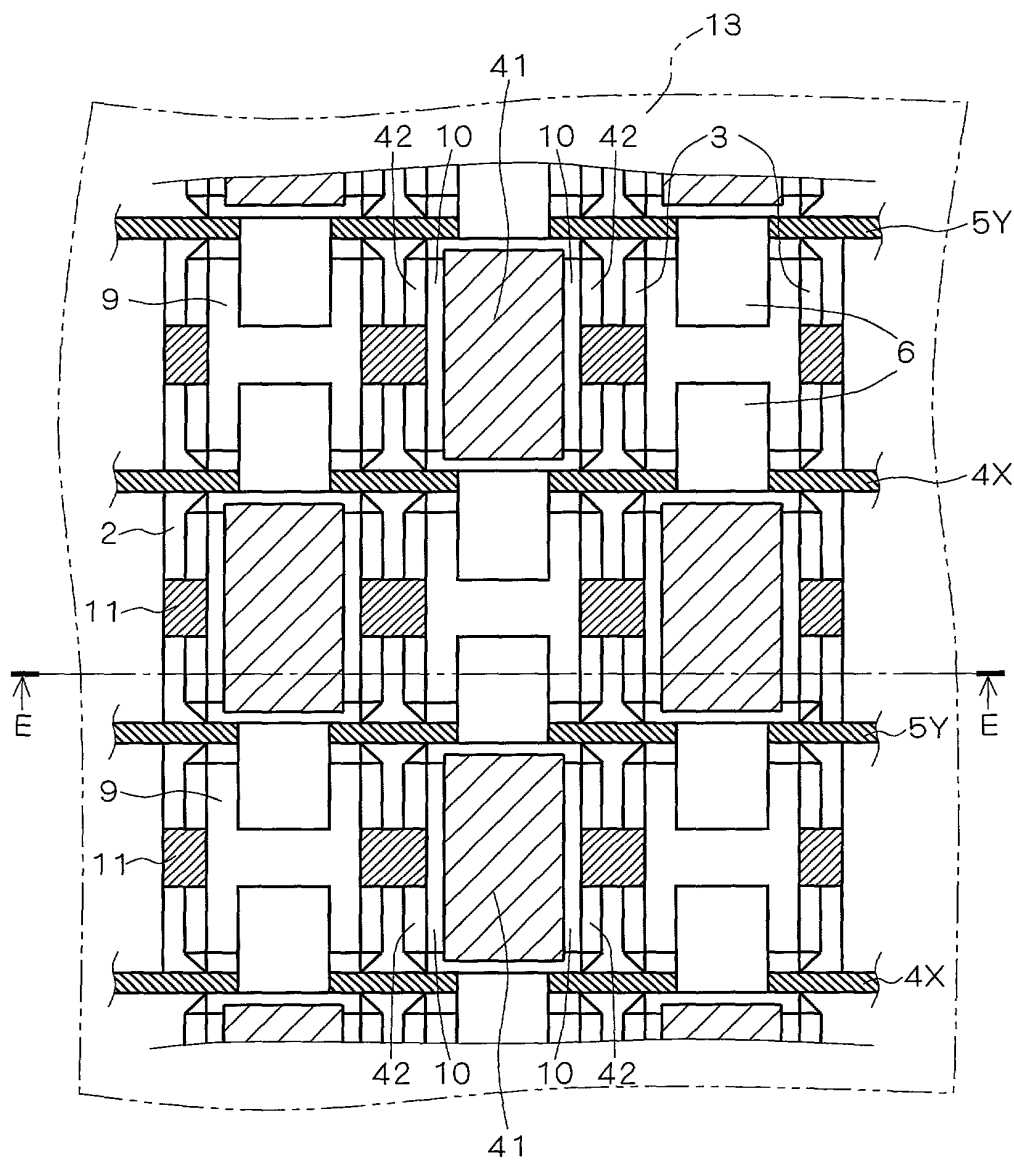


FIG. 13

106



$F / G. \quad 14$

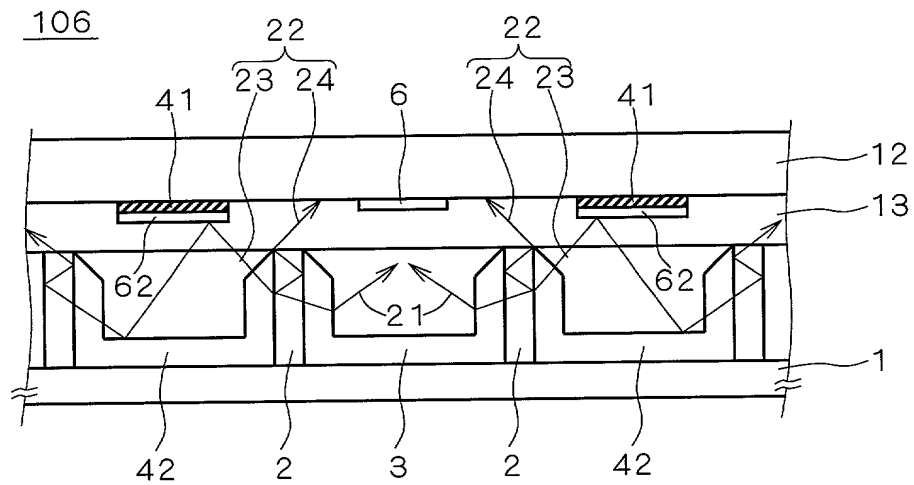


FIG. 10 is a cross-sectional view of a multi-layered structure 107. The structure consists of alternating layers of material 9 and material 6. A central vertical channel 71 is present. Horizontal layers are labeled 4X and 5Y. A dashed line 13 indicates a boundary. Arrows F and G indicate forces or directions.

FIG. 16

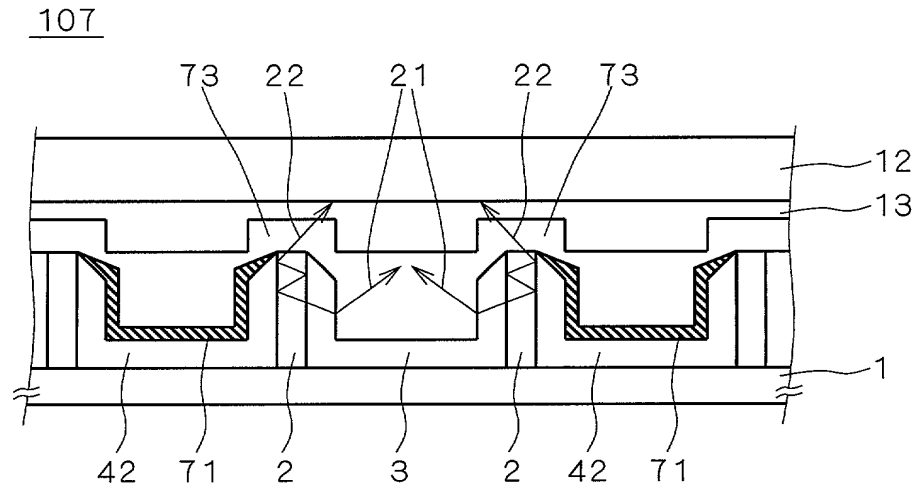


FIG. 17

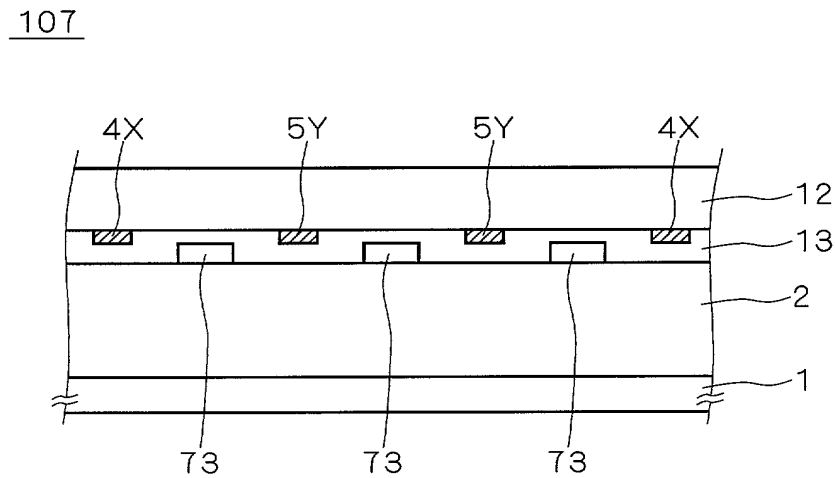


FIG. 18

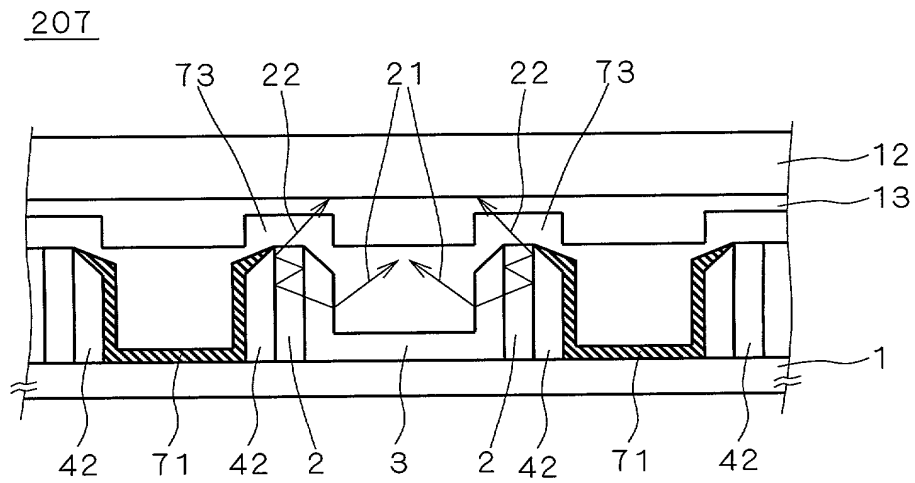


FIG. 19

108

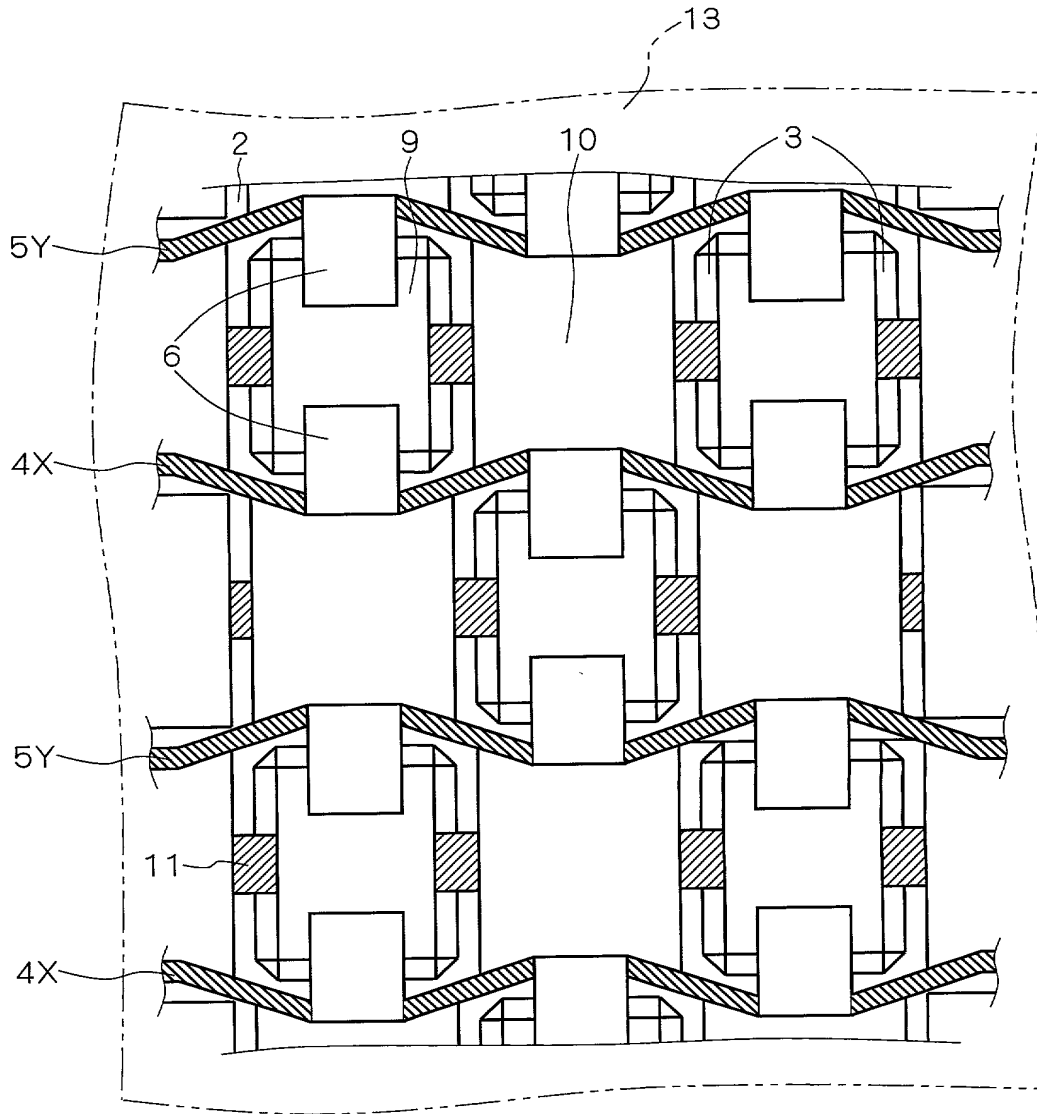


FIG. 20

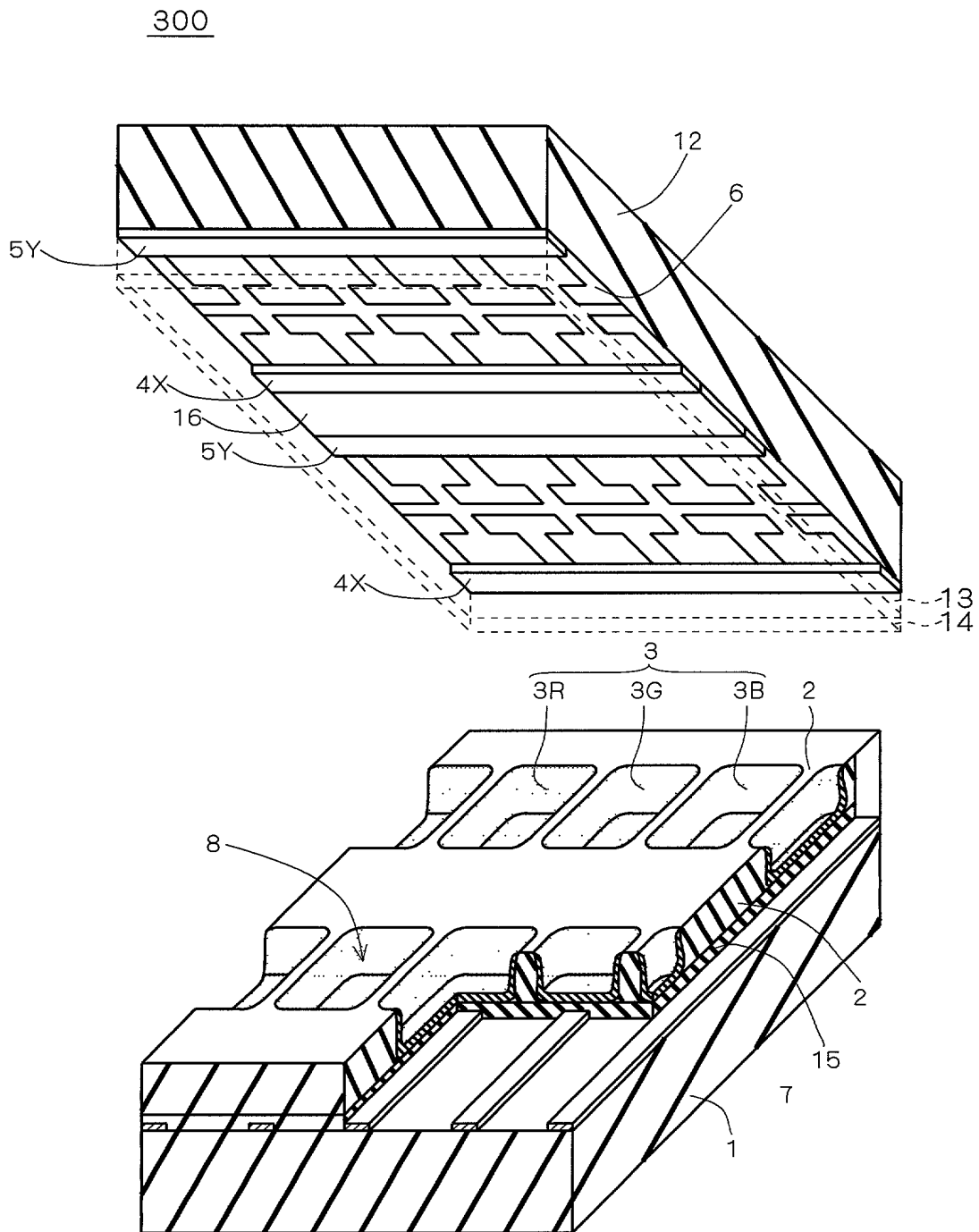


FIG. 21

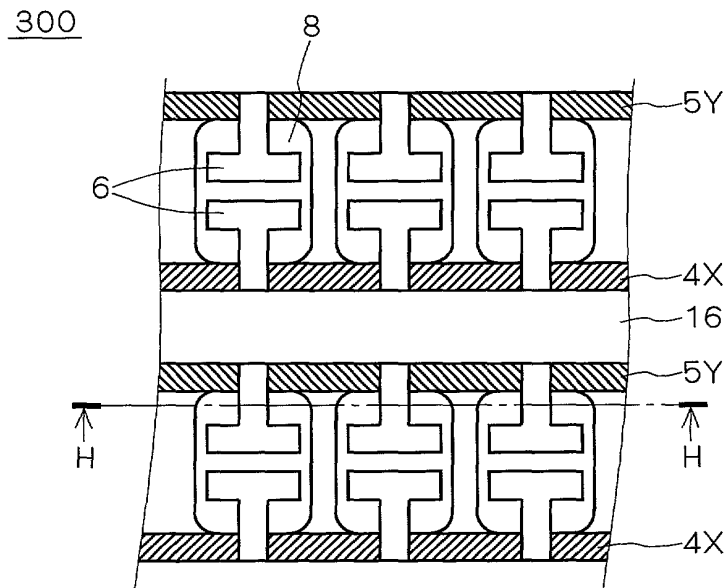


FIG. 22

